Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|-----------------|----------------|
| Dal Jae Lee | 08/03/2007 |
| Nam Ju Cho | 08/03/2007 |
| Soo-San Park | 08/03/2007 |
| Jaepil Kim | 08/03/2007 |
| Sungpil Hur | 08/03/2007 |
| Hyeong Kug Jin | 08/03/2007 |
| JongMin Han | 08/03/2007 |
| SungJae Lim | 08/03/2007 |
| HyoungChul Kwon | 08/03/2007 |

RECEIVING PARTY DATA

| Name: | STATS ChipPAC Ltd. |
|-----------------|--------------------|
| Street Address: | 5 Yishun Street 23 |
| City: | Singapore |
| State/Country: | SINGAPORE |
| Postal Code: | 768442 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 11833646 |

CORRESPONDENCE DATA

Fax Number: (408)738-0881

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: (408) 738-0592

Email: efiling@ishimarulaw.com

Correspondent Name: Mikio Ishimaru

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Address Line 2: 333 W. El Camino Real, Suite # 330

PATENT REEL: 019646 FRAME: 0236 340.00 11

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| Address Line 4: Sunnyvale, CA | LIFORNIA 94087 |
|---|----------------|
| ATTORNEY DOCKET NUMBER: | 27-298 |
| NAME OF SUBMITTER: | Mikio Ishimaru |
| Total Attachments: 5 source=27-298_ASSIGNMENT#page1.tif source=27-298_ASSIGNMENT#page2.tif source=27-298_ASSIGNMENT#page3.tif source=27-298_ASSIGNMENT#page4.tif source=27-298_ASSIGNMENT#page5.tif | |

PATENT REEL: 019646 FRAME: 0237 Docket No.: 27-298

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH MOLDING VENTS

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, <u>STATS ChipPAC Ltd.</u>, a Corporation of the <u>Republic of Singapore</u>, having a place of business at <u>5 Yishun Street 23</u>, <u>Singapore 768442</u> (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

- 1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
- 2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
- 3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignce, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
- 4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

| al ten | Aug 63 2000 |
|--------------------|--------------------|
| Dal Jae Lee | Date |
| - Pour | TY Woo |
| Witness Signature | Witness Signature |
| lee, Sang Ho | MA Jong Woo |
| Print Witness Name | Print Witness Name |
| Aug 03, 2007 | Aug 07, 2007 |
| Date | Date |

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

| (Mo | Aug. 03, 2007 |
|--------------------|--------------------|
| Nam Ju Cho | Date |
| Vitness Signature | THW. |
| Witness Signature | Witness Signature |
| Lee Sang He | HA Jong Wee |
| Print Witness Name | Print Witness Name |
| Aug. 03 2007 | Aug et, 2007 |
| Date | Date |

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

| , Carl | Aug 63 2001 |
|--------------------|--------------------|
| Soo-San Park | Date |
| Jan | Tyvw. |
| Witness Signature | Witness Signature |
| Lee Sing Ho | HA JongWoo |
| Print Witness Name | Print Witness Name |
| Aug 03 2007 | Ang.03 2007 |
| Date | Date |

Docket No.: 27-298

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Jaepil Kim Witness Signature Witness Signature HA SongWoo Print Witness Name Lee. Sawa kto Print Witness Name Aug 03 >007 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Aug 03 2007
Date

Ang Ohon Sungpil Hur Witness Signature Witness Signature HA Jong Woo Print Witness Name Lee Sing late Print Witness Name Aug. 03, 2007
Date

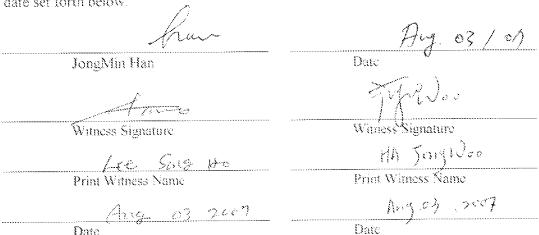
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

| | 8/3/67_ |
|--------------------|--------------------|
| Hyeong Kug Jin | Date / |
| Anno | Tyllo |
| Witness Signature | Withless Signature |
| Lee Sove He | HA Jong Woo |
| Print Witness Name | Print Witness Name |
| Aug 63 7007 | Aug 03, 2007 |

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Date

Date



IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

| far- | A44, 03 1 19 |
|---------------------|--------------------|
| SungJae Lim | Date |
| - fare s | TYW00 |
| Witness Signature | Witness Signature |
| LEE SOME UP | MA JongWoo |
| Print Witness Name | Print Witness Name |
| Aug 03 2007 | Aug. 03, 2007 |
| Date | Date |

Docket No.: 27-298 ASSIGNMENT

| Jan | Dy 03/04 |
|---|--------------------|
| Hyoung Chal Kwon | Date O |
| <u>— fare</u> o | TY Wo. |
| Wirness Signature | Witness Signature |
| Lter Sing Ho | MA Jongwoo |
| Print Witness Name | Print Witness Name |
| Aug. 12 207 | Aug 03 - 2007 |
| | Date |